

All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
Body	BRASS	NPGR
Center contact	BRASS	NPGR
Outer contact		
Insulator	PTFE/LCP/PEEK	
Gasket		
Others parts	PTFE/LCP/PEEK	
-	-	-
-	-	-

Radiall 🏹 🕯		STRAI	GHT MALE RE	Technical Data Sheet ECEPTACLE FOR SMT SLIDE TYPE - REEL OF 400
PAGE 2/5 ISSUE 130	8C SERIES	SMP-MAX		PART NUMBER <b>R222M00740</b>
ELECTRICAL C	Standar 400	rd Cc	Unit Unit Inntact us	Other Contact us
npedance requency SWR <b>1.25*</b> sertion loss F leakage oltage rating ielectric withstanding voltage sulation resistance	0-6 ( + 0.0000 ) 0.15* - - ( NA - 335 ) 1000 )	Ω GHz < F(GHz) Maxi √F(GHz) dB Ma F(GHz)) dB Ma Veff Maxi Veff Maxi Veff mini MΩ mini	axi Opera Herma	ENVIRONMENTAL ating temperature -55/+165 ℃ etic seal NA Atm.cm3/s I leakage NA
MECHANICAL C enter contact retention Axial force – Mating End Axial force – Opposite end Torque Recommended torque Mating Panel nut Mating life Weight	NA N.cr NA N.cr	7 N mini 7 N mini JA N.cm mini n	Assemb Others: *VSWR *Coaxia *Slide t Typical 0-3GHz Power >300W0 Radial	SPECIFICATION         DITER CHARACTERISTICS         by instruction:         ************************************

<section-header><page-header><section-header><section-header><section-header><section-header></section-header></section-header></section-header></section-header></page-header></section-header>	Radiall	тм	STRAIGH	IT MALE RECE		SMT SLIDE TYPE - REEL OF 400
<ol> <li>Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch ). Verify that the edges of zone are clean.</li> <li>Placement of the receptacle on the mounting zone with an automatic machine of 'pi and place' type. A video camera is recommended for positioning of the component Adhesive agents must not be used on the receptacle.</li> <li>This process of soldering has been tested with convection oven .Below please find, the typical profile to use.</li> <li>The cleaning of printed circuit boards is not obliged .</li> <li>Verification of solder joints and position of the component by visual inspection.</li> <li>The remember the typical profile to use.</li> <li>The cleaning of printed circuit boards is not obliged .</li> <li>Verification of solder joints and position of the component by visual inspection.</li> <li>The remember the typical profile to use.</li> <li>The remember typical profile to use.</li> <li>The remember the typical profile to use.</li> <li>The remember typical profile to use.</li> <li>The cleaning of printed circuit boards is not obliged .</li> <li>The remember typical profile to use.</li> <li>The remember typical profile t</li></ol>	PAGE <b>3/5</b>	ISSUE 1308C	SERIES SMP-MAX		PART NUM	MBER <b>R222M00740</b>
We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch ). Verify that the edges of zone are clean. 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pi and place' type. A video camera is recommended for positioning of the component Adhesive agents must not be used on the receptacle. 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use. 4. The cleaning of printed circuit boards is not obliged . Verification of solder joints and position of the component by visual inspection. $\frac{\text{TEMPERATURE PROFILE}}{\int_{0}^{0} \int_{0}^{0} \int_{0}^{0}$			SOLDER P	ROCE	DURE	
and place' type. A video camera is recommended for positioning of the component Adhesive agents must not be used on the receptacle. 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use. 4. The cleaning of printed circuit boards is not obliged . Verification of solder joints and position of the component by visual inspection. TEMPERATURE PROFILE $Verification of solder joints and position of the component by visual inspection. \frac{Present Area}{Present Area} + Present Are$	We recom We advise	mend a low a thickness	residue flux.	•	-	
<text><text><figure></figure></text></text>	and place'	type. A vide	eo camera is recom	mended	for positio	
<text><figure></figure></text>			-	d with co	nvection	oven .Below please
$\frac{\text{remerature rising Area}}{\text{trameerature rising Area}} \frac{\text{value}}{160  down of the sector of$	4. The cleani	ng of printe	d circuit boards is	not oblige	ed.	
$\frac{1}{260} + \frac{1}{260} + \frac{1}$	Verification o	f solder join	ts and position of t	he compo	onent by v	visual inspection.
$\frac{1}{260} + \frac{1}{260} + \frac{1}$						
$\frac{1}{260^{-0}} \frac{1}{10^{-0}} \frac{1}{10^{-0}}$						
$\frac{1}{200^{-1}} \int_{100^{-1}}^{100^{-1}} \int_{100^{-1}}^$		Area	Preheat Area	Reflow Area	Forced Cooling A	rea
$\frac{1}{200^{\circ}} \frac{1}{10^{\circ}} $		250			<b>\</b>	
$\frac{1}{1000} \int_{0}^{0} \int_{$					Max peak temperature: 260°C	
Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description       Image: Description of the	õ	200		/	+	
Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description       Image: Description of the	ature (°	150				
Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description of the system       Image: Description of the system       Image: Description of the system         Image: Description       Image: Description of the	ampera					
0       60       120       180       240       300         Time (seconds)         Time (seconds)	Ţe	100		+		
0       60       120       180       240       300         Time (seconds)         Time (seconds)						
Parameter     Value     Unit       Temperature rising Area     1 - 4     °C/sec       Max Peak Temperature     260     °C       Max dwell time @260 °C     10     sec       Min dwell time @235 °C     20     sec       Max dwell time @235 °C     60     sec       Temperature drop in cooling Area     -1 to - 4     °C/sec		30		1		
ParameterValueUnitTemperature rising Area1 - 4°C/secMax Peak Temperature260°CMax dwell time @260 °C10secMin dwell time @235 °C20secMax dwell time @235 °C60secTemperature drop in cooling Area-1 to - 4°C/sec		0	60 120	180	240	300
Temperature rising Area1 - 4℃/secMax Peak Temperature260℃Max dwell time @260 ℃10secMin dwell time @235 ℃20secMax dwell time @235 ℃60secTemperature drop in cooling Area-1 to - 4℃/sec						
Temperature rising Area1 - 4℃/secMax Peak Temperature260℃Max dwell time @260 ℃10secMin dwell time @235 ℃20secMax dwell time @235 ℃60secTemperature drop in cooling Area-1 to - 4℃/sec		Paramet	er	Value	Unit	
Max dwell time @260 °C10secMin dwell time @235 °C20secMax dwell time @235 °C60secTemperature drop in cooling Area-1 to - 4°C/sec						
Min dwell time @235 °C20secMax dwell time @235 °C60secTemperature drop in cooling Area-1 to - 4°C/sec					-	
Max dwell time @235 °C60secTemperature drop in cooling Area-1 to - 4°C/sec						
Max dwell time above 100 °C 420 sec			-			
		Max dwe	II time above 100°C	420	Sec	



